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## CLAIMS

What is claimed is:

- 1           1.     A method comprising:  
2           placing a wafer on a chuck, the wafer having a front side attached to a tape;  
3           obtaining a scribe pattern on the front side through the tape by an imaging  
4           sensor; and  
5           marking an alignment pattern on a back side of the wafer using a laser based on  
6           the scribe pattern, the laser being mounted above the chuck.
- 1           2.     The method of claim 1 wherein placing the wafer comprises:  
2           placing the wafer front side up on the chuck.
- 1           3.     The method of claim 2 wherein obtaining the scribe pattern comprises:  
2           obtaining the scribe pattern on the front side by the imaging sensor mounted  
3           above the wafer.
- 1           4.     The method of claim 3 further comprising:  
2           flipping the wafer to turn the back side up.
- 1           5.     The method of claim 1 wherein placing the wafer comprises:  
2           placing the wafer back side up on the chuck.
- 1           6.     The method of claim 5 wherein obtaining the scribe pattern comprises:  
2           obtaining the scribe pattern on the front side by the imaging sensor mounted  
3           underneath the wafer.

1           7.     The method of claim 1 wherein marking the alignment pattern  
2 comprises:  
3           receiving the scribe pattern from the imaging sensor; and  
4           emitting a laser beam from the laser to etch the alignment pattern on the back  
5 side, the alignment pattern being directly opposite to the scribe pattern.

1           8.     The method of claim 1 further comprising:  
2           recognizing the alignment pattern on the back side of the wafer.

1           9.     The method of claim 8 further comprising:  
2           cutting the back side of the wafer based on the alignment pattern.

1           10.    The method of claim 1 further comprising:  
2           recognizing the scribe pattern; and  
3           saving the scribe pattern in a memory.

1           11.    A method comprising:  
2           controlling an imaging sensor to obtain a scribe pattern on a front side of a  
3 wafer placed on a chuck, the front side being attached a tape;  
4           recognizing the scribe pattern; and  
5           controlling a laser to mark an alignment pattern on a back side of the wafer  
6 based on the scribe pattern, the laser being mounted above the chuck.

1           12.    The method of claim 11 wherein controlling the imaging sensor  
2 comprises:  
3           controlling the imaging sensor mounted above the wafer.

1           13.    The method of claim 11 wherein controlling the imaging sensor  
2 comprises:

3           controlling the imaging sensor mounted underneath the wafer.

1           14.    The method of claim 11 wherein controlling the laser comprises:  
2           emitting a laser beam from the laser to etch the alignment pattern on the back  
3 side, the alignment pattern being directly opposite to the scribe pattern.

1           15.    The method of claim 11 further comprising:  
2           activating a flipping mechanism to turn the back side of the wafer up.

1           16.    The method of claim 11 further comprising:  
2           saving the scribe pattern in a memory.

1           17.    The method of claim 11 further comprising:  
2           recognizing the alignment pattern on the back side of the wafer.

1           18.    The method of claim 17 further comprising:  
2           controlling a cutter to cut the back side of the wafer based on the alignment  
3 pattern.

1           19.    An article of manufacture comprising:  
2           a machine-accessible medium including data that, when accessed by a machine,  
3 causes the machine to:  
4                 control an imaging sensor to obtain a scribe pattern on a front side of a  
5 wafer placed on a chuck, the front side being attached a tape;  
6                 recognize the scribe pattern; and

7                   control a laser to mark an alignment pattern on a back side of the wafer  
8                   based on the scribe pattern, the laser being mounted above the chuck.

1           20.     The article of manufacture of claim 19 wherein the data causing the  
2 machine to control the imaging sensor comprises data that, when accessed by the  
3 machine, causes the machine to:

4           control the imaging sensor mounted above the wafer.

1           21.     The article of manufacture of claim 19 wherein the data causing the  
2 machine to control the imaging sensor comprises data that, when accessed by the  
3 machine, causes the machine to:

4           control the imaging sensor mounted underneath the wafer.

1           22.     The article of manufacture of claim 19 wherein the data causing the  
2 machine to control the laser comprises data that, when accessed by the machine, causes  
3 the machine to:

4           emit a laser beam from the laser to etch the alignment pattern on the back side,  
5 the alignment pattern being directly opposite to the scribe pattern.

1           23.     The article of manufacture of claim 19 wherein the data further  
2 comprises data that, when accessed by the machine, causes the machine to:

3           activate a flipping mechanism to turn the back side of the wafer up.

1           24.     The article of manufacture of claim 19 wherein the data further  
2 comprises data that, when accessed by the machine, causes the machine to:

3           save the scribe pattern in a memory.

1           25.     The article of manufacture of claim 19 wherein the data further  
2 comprises data that, when accessed by the machine, causes the machine to:  
3           recognize the alignment pattern on the back side of the wafer.

1           26.     The article of manufacture of claim 25 wherein the data further  
2 comprises data that, when accessed by the machine, causes the machine to:  
3           control a cutting mechanism to cut the back side of the wafer based on the  
4 alignment pattern.

1           27.     A system comprising:  
2           a chuck to hold a wafer, the wafer having a front side attached to a tape;  
3           an imaging sensor to obtain a scribe pattern on the front side through the tape;  
4 and  
5           a laser mounted above the chuck to mark an alignment pattern on a back side of  
6 the wafer based on the scribe pattern.

1           28.     The system of claim 27 wherein the chuck holds the wafer front side up.

1           29.     The system of claim 26 wherein the imaging sensor is mounted above  
2 the wafer.

1           30.     The system of claim 27 further comprising:  
2           a flipping mechanism to turn up the back side of the wafer.

1           31.     The system of claim 25 wherein the chuck holds the wafer back side up.

1           32.     The system of claim 29 wherein the imaging sensor is mounted  
2 underneath the wafer.

1           33.     The system of claim 25 wherein the laser emits a laser beam from the  
2     laser to etch the alignment pattern on the back side, the alignment pattern being directly  
3     opposite to the scribe pattern.

1           34.     The system of claim 25 further comprising:  
2             a processing unit to recognize the alignment pattern on the back side of the  
3     wafer.

1           35.     The system of claim 32 further comprising:  
2             a cutter to cut the back side of the wafer based on the alignment pattern.

1           36.     The system of claim 32 wherein the processing unit recognizes the  
2     scribe pattern and saves the scribe pattern in a memory.